



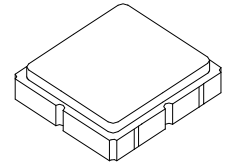
AEC-Q200
This component was always
RoHS compliant from the first
date of manufacture.

- *Steep Roll-off Filter for 869.00 MHz Unlicensed Band*
- *Complies with Directive 2002/95/EC (RoHS)*
- *No Matching Required for Operation in 50Ω Environment*



SF2137E

**869.00 MHz
SAW Filter**



SM3030-6

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	17	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			869.00		MHz
Bandwidth, 1 dB				11		
Bandwidth, 3 dB				17		
Insertion Loss, 868 to 870 MHz	IL			2.8	4.0	dB
Amplitude Ripple, 868 to 870 MHz				0.2	1.5	dB _{P-P}
Attenuation Referenced to 0 dB:						dB
825 to 828 MHz			40	47		
835 to 842 MHz			30	39		
891 to 894 MHz			30	42		
910 to 913 MHz			40	47		
Source Impedance	Z_s			50		Ω
Load Impedance	Z_L			50		Ω

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint		
Lid Symbolization, Y=year, WW=week, S=shift, Dot=pin 1 indicator	711, YWWS		
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel	
	Reel Size 13 Inch	3000 Pieces/Reel	

Electrical Connections

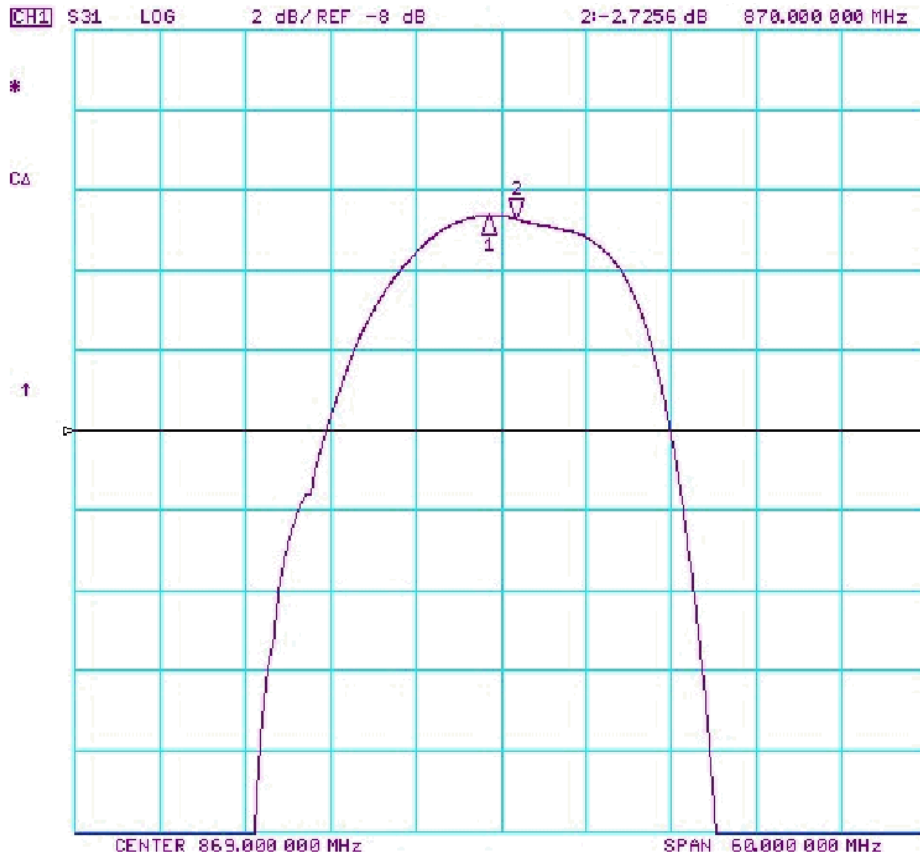
Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others



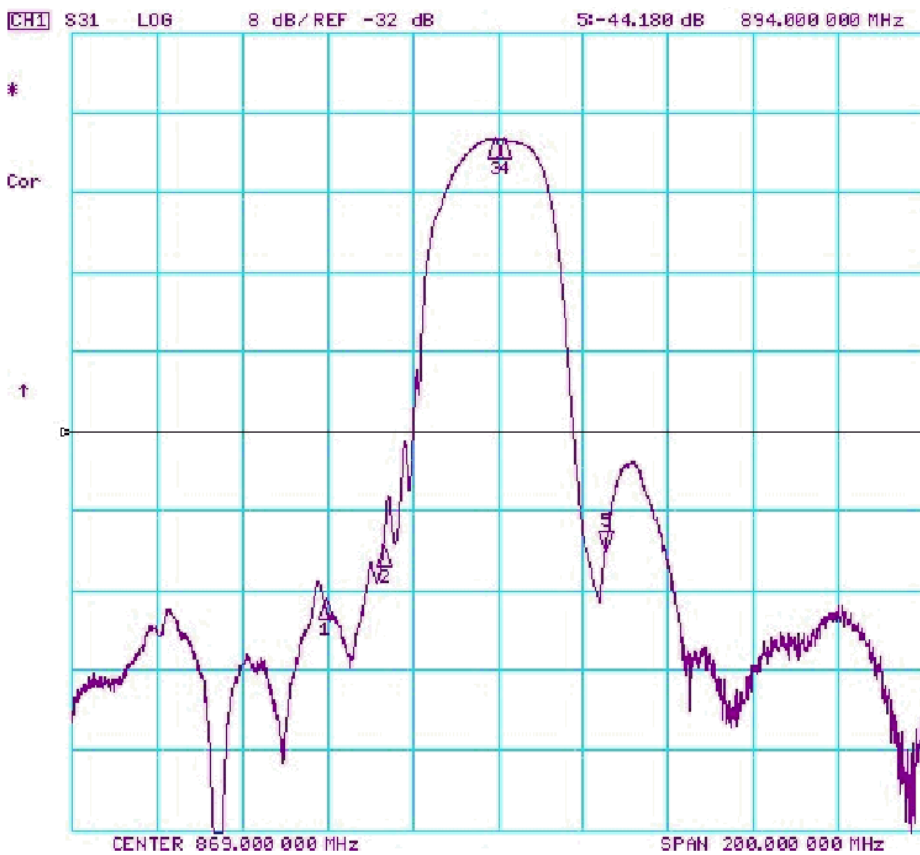
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

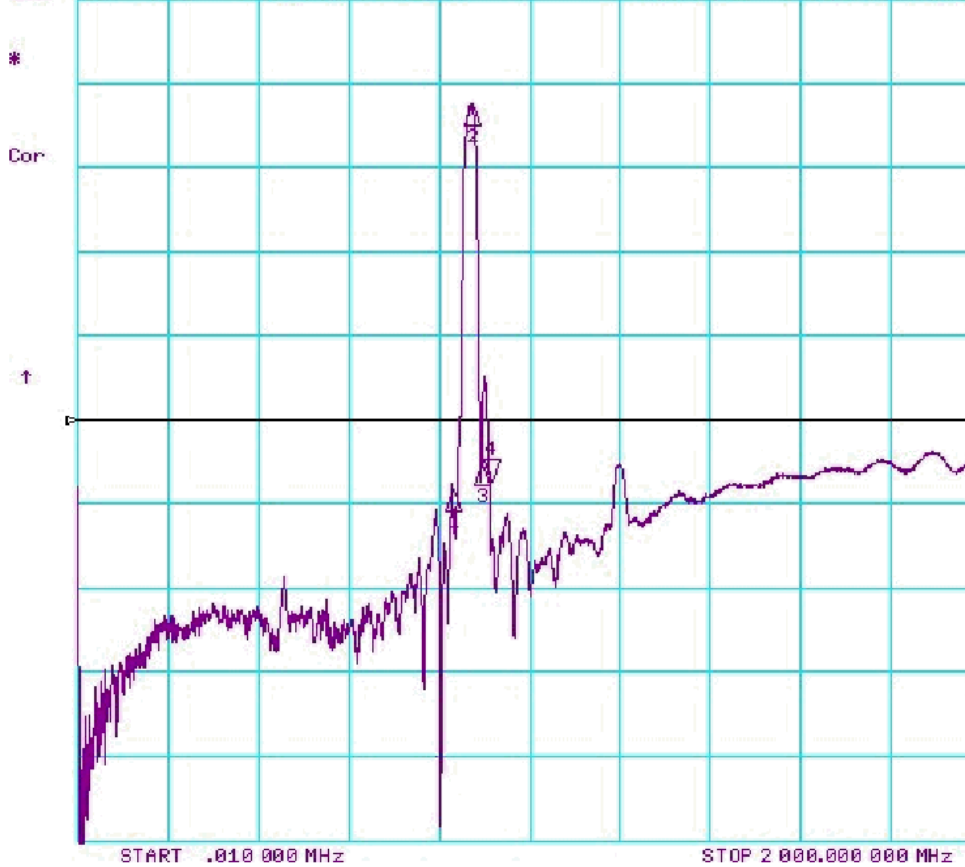


CH1 Markers
 1i-2.6412 dB
 868.000 MHz



CH1 Markers
 1i-43.024 dB
 828.000 MHz
 2i-43.517 dB
 842.000 MHz
 3i-2.6378 dB
 868.000 MHz
 4i-2.7213 dB
 870.000 MHz

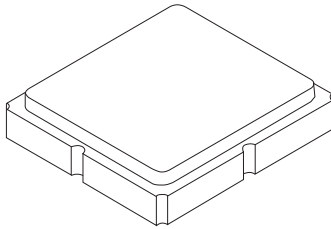
CH1 S31 LOG 10 dB/REF -40 dB 41-47.219 dB 910.000 000 MHz



CH1 Markers
1:-48.523 dB
820.000 MHz
2:-2.5911 dB
869.000 MHz
3:-45.496 dB
891.000 MHz

SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

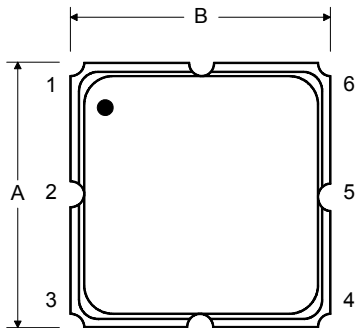
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

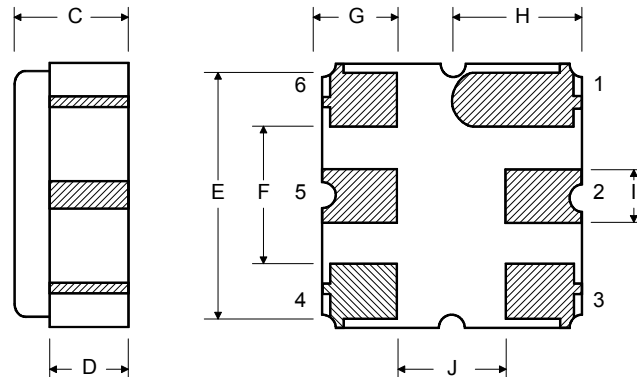
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

Top View

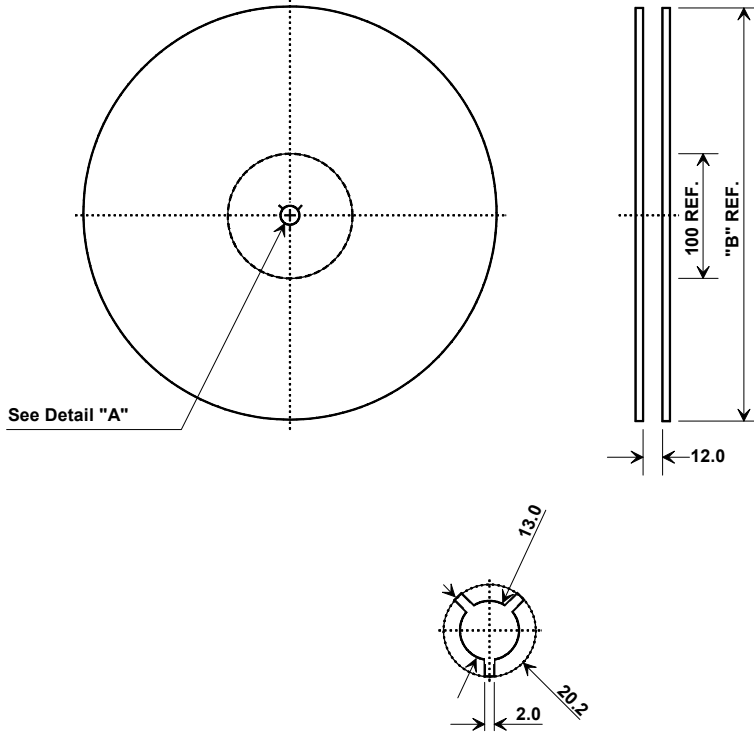


Bottom View



Tape and Reel Specifications

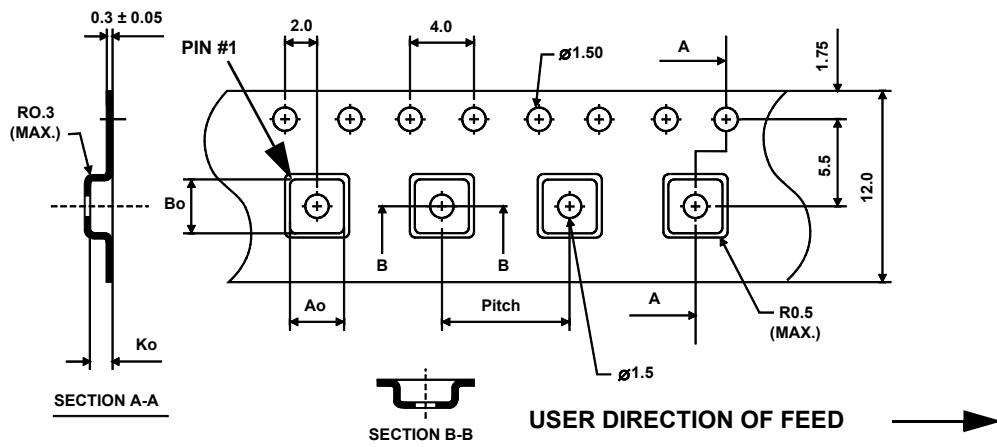
Tape and Reel Standard per ANSI/EIA-481



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

